

GaAs INTEGRATED CIRCUIT $\mu PG2406TB$

0.01 to 3.0 GHz SPDT SWITCH

DESCRIPTION

The μ PG2406TB is a GaAs MMIC for L, S-band SPDT (<u>Single Pole Double Throw</u>) switch which were designed for mobile phone and another L, S-band application.

This device can operate 2 control switching by control voltage 1.8 to 5.3 V. This device can operate frequency from 0.01 to 3.0 GHz, having the low insertion loss and high isolation.

This device is housed in a 6-pin super minimold package. And this package is able to high-density surface mounting.

FEATURES

•	Switch control voltage	: V _{cont (H)} = 1.8 to 5.3 V (2.7 V TYP.)
		: $V_{cont (L)} = -0.2 \text{ to } +0.2 \text{ V} (0 \text{ V TYP.})$
٠	Low insertion loss	: Lins = 0.40 dB TYP. @ f = 1.0 GHz, Vcont (H) = 2.7 V, Vcont (L) = 0 V
		: Lins = 0.47 dB TYP. @ f = 2.5 GHz, V cont (H) = 2.7 V, V cont (L) = 0 V
•	High isolation	: ISL = 27 dB TYP. @ f = 1.0 GHz, V _{cont} (H) = 2.7 V, V _{cont} (L) = 0 V
		: ISL = 17 dB TYP. @ f = 2.5 GHz, Vcont (H) = 2.7 V, Vcont (L) = 0 V
•	Handling power	: Pin (0.1 dB) = +29.0 dBm TYP. @ f = 2.0/2.5 GHz, V _{cont} (H) = 2.7 V, V _{cont} (L) = 0 V
		: Pin (1 dB) = +30.5 dBm TYP. @ f = 0.5 to 3.0 GHz, V_{cont} (H) = 2.7 V, V_{cont} (L) = 0 V

• High-density surface mounting : 6-pin super minimold package ($2.0 \times 1.25 \times 0.9$ mm)

APPLICATIONS

- L, S-band digital cellular or cordless telephone
- W-LAN, WLL and Bluetooth[™] etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
<i>µ</i> РG2406ТВ-Е4	μPG2406TB-E4-A	6-pin super minimold (Pb-Free)	G5L	 Embossed tape 8 mm wide Pin 4, 5, 6 face the perforation side of the tape Qty 3 kpcs/reel

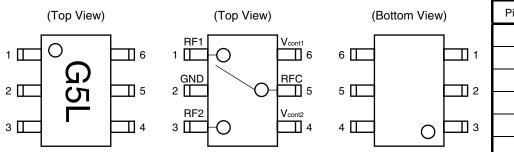
Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: µPG2406TB

Caution Although this device is designed to be as robust as possible, ESD (Electrostatic Discharge) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions must be employed at all times.

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PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	RF1
2	GND
3	RF2
4	V _{cont2}
5	RFC
6	Vcont1

SW TRUTH TABLE

ON Path	Vcont1	V _{cont2}
RFC-RF1	High	Low
RFC-RF2	Low	High

ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Switch Control Voltage		Vcont	+6.0 ^{Note}	V
Input Power f = 0.01 to 0.5 GHz		Pin1	+24.0	dBm
	f = 0.5 to 3.0 GHz	Pin2	+31.0	
Operating Ambient Temperature		TA	-45 to +85	°C
Storage Temper	ature	Tstg	–55 to +150	°C

Note $|V_{cont1} - V_{cont2}| \le 6.0 V$

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Switch Control Voltage (H)	Vcont (H)	1.8	2.7	5.3	V
Switch Control Voltage (L)	Vcont (L)	-0.2	0	0.2	V

ELECTRICAL CHARACTERISTICS

(TA = +25°C, V_{cont} (H) = 2.7 V, V_{cont} (L) = 0 V, DC blocking capacitors = 56 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	Lins1	f = 0.01 to 0.05 GHz ^{Note 1}	-	0.40	-	dB
Insertion Loss 2	Lins2	f = 0.05 to 0.5 GHz ^{Note 2}	_	0.40	0.45	dB
Insertion Loss 3	Lins3	f = 0.5 to 1.0 GHz	_	0.40	0.45	dB
Insertion Loss 4	Lins4	f = 1.0 to 2.0 GHz	-	0.45	0.50	dB
Insertion Loss 5	Lins5	f = 2.0 to 2.5 GHz	-	0.47	0.55	dB
Insertion Loss 6	Lins6	f = 2.5 to 3.0 GHz	-	0.53	0.60	dB
Isolation 1	ISL1	f = 0.01 to 0.05 GHz ^{Note 1}	_	27	-	dB
Isolation 2	ISL2	f = 0.05 to 0.5 GHz ^{Note 2}	23	27	-	dB
Isolation 3	ISL3	f = 0.5 to 1.0 GHz	23	27	-	dB
Isolation 4	ISL4	f = 1.0 to 2.0 GHz	16	19	-	dB
Isolation 5	ISL5	f = 2.0 to 2.5 GHz	14	17	_	dB
Isolation 6	ISL6	f = 2.5 to 3.0 GHz	14	17	_	dB
Input Return Loss 1	RLin1	f = 0.01 to 0.05 GHz ^{Note 1}	-	20	-	dB
Input Return Loss 2	RLin2	f = 0.05 to 0.5 GHz ^{Note 2}	15	20	-	dB
Input Return Loss 3	RLin3	f = 0.5 to 3.0 GHz	15	20	-	dB
Output Return Loss 1	RLout1	f = 0.01 to 0.05 GHz ^{Note 1}	_	20	-	dB
Output Return Loss 2	RLout2	f = 0.05 to 0.5 GHz ^{Note 2}	15	20	-	dB
Output Return Loss 3	RLout3	f = 0.5 to 3.0 GHz	15	20	-	dB
0.1 dB Loss Compression	Pin (0.1 dB)	f = 2.0/2.5 GHz	+26.0	+29.0	-	dBm
Input Power ^{Note 3}		f = 0.5 to 3.0 GHz	_	+29.0	_	dBm
1 dB Loss Compression	Pin (1 dB)	f = 0.5 to 3.0 GHz	_	+30.5	-	dBm
Input Power ^{Note 4}						
2nd Harmonics	2fo	f = 2.0/2.5 GHz, P _{in} = +20 dBm	65	75	_	dBc
3rd Harmonics	3fo	f = 2.0/2.5 GHz, P _{in} = +20 dBm	65	75	_	dBc
Intermodulation Intercept Point	IIP₃	f = 0.5 to 3.0 GHz, 2 tone, 5 MHz spicing	-	+60	-	dBm
Switch Control Current	Icont	No RF input	_	0.2	20	μA
Switch Control Speed	tsw	50% CTL to 90/10% RF	-	50	500	ns

Notes 1. DC blocking capacitors = $10\ 000\ pF$ at f = $0.01\ to\ 0.05\ GHz$

- **2.** DC blocking capacitors = 1000 pF at f = 0.05 to 0.5 GHz
- **3.** Pin (0.1 dB) is measured the input power level when the insertion loss increases more 0.1 dB than that of linear range.
- 4. Pin (1 dB) is measured the input power level when the insertion loss increases more 1 dB than that of linear range.

Caution This device is used it is necessary to use DC blocking capacitors.

The value of DC blocking capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system. The range of recommended DC blocking capacitor value is less than 56 pF.

ELECTRICAL CHARACTERISTICS

(TA = +25°C, V_{cont} (H) = 1.8 V, V_{cont} (L) = 0 V, DC blocking capacitors = 56 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 7	Lins7	f = 0.01 to 0.05 GHz ^{Note 1}	-	0.40	-	dB
Insertion Loss 8	Lins8	f = 0.05 to 0.5 GHz ^{Note 2}	-	0.40	0.46	dB
Insertion Loss 9	Lins9	f = 0.5 to 1.0 GHz	-	0.40	0.47	dB
Insertion Loss 10	Lins10	f = 1.0 to 2.0 GHz	-	0.46	0.52	dB
Insertion Loss 11	Lins11	f = 2.0 to 2.5 GHz	-	0.48	0.57	dB
Insertion Loss 12	Lins12	f = 2.5 to 3.0 GHz	-	0.54	0.62	dB
Isolation 7	ISL7	f = 0.01 to 0.05 GHz ^{Note 1}	-	27	-	dB
Isolation 8	ISL8	f = 0.05 to 0.5 GHz ^{Note 2}	23	27	-	dB
Isolation 9	ISL9	f = 0.5 to 1.0 GHz	23	27	-	dB
Isolation 10	ISL10	f = 1.0 to 2.0 GHz	16	19	-	dB
Isolation 11	ISL11	f = 2.0 to 2.5 GHz	14	17	-	dB
Isolation 12	ISL12	f = 2.5 to 3.0 GHz	14	17	-	dB
Input Return Loss 4	RLin4	f = 0.01 to 0.05 GHz ^{Note 1}	-	20	-	dB
Input Return Loss 5	RLin5	f = 0.05 to 0.5 GHz ^{Note 2}	15	20	-	dB
Input Return Loss 6	RLin6	f = 0.5 to 3.0 GHz	15	20	-	dB
Output Return Loss 4	RL _{out} 4	f = 0.01 to 0.05 GHz ^{Note 1}	-	20	-	dB
Output Return Loss 5	RLout5	f = 0.05 to 0.5 GHz ^{Note 2}	15	20	-	dB
Output Return Loss 6	RLout6	f = 0.5 to 3.0 GHz	15	20	-	dB
0.1 dB Loss Compression	P in (0.1 dB)	f = 2.0/2.5 GHz	+19.0	+22.0	-	dBm
Input Power ^{Note 3}		f = 0.5 to 3.0 GHz	-	+22.0	-	dBm
1 dB Loss Compression Input Power ^{Note 4}	Pin (1 dB)	f = 0.5 to 3.0 GHz	_	+25.0	-	dBm
Switch Control Current	Icont	No RF input	_	0.2	20	μA
Switch Control Speed	tsw	50% CTL to 90/10% RF	_	50	500	ns

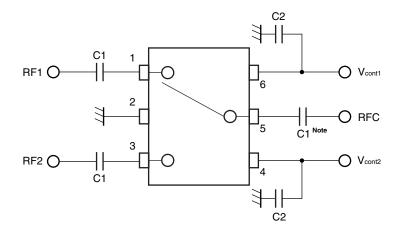
Notes 1. DC blocking capacitors = $10\ 000\ pF$ at f = $0.01\ to\ 0.05\ GHz$

- 2. DC blocking capacitors = 1 000 pF at f = 0.05 to 0.5 GHz
- **3.** P_{in (0.1 dB)} is measured the input power level when the insertion loss increases more 0.1 dB than that of linear range.
- **4.** P_{in (1 dB)} is measured the input power level when the insertion loss increases more 1 dB than that of linear range.

Caution This device is used it is necessary to use DC blocking capacitors.

The value of DC blocking capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system. The range of recommended DC blocking capacitor value is less than 56 pF.

EVALUATION CIRCUIT



 Note
 C1 : 0.01 to 0.05 GHz
 10 000 pF

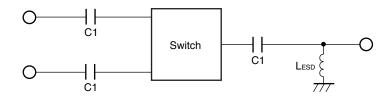
 : 0.05 to 0.5 GHz
 1 000 pF

 : 0.5 to 3.0 GHz
 56 pF

 C2 : 1 000 pF

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

APPLICATION INFORMATION



- LESD provides a means to increase the ESD protection on a specific RF port, typically the port attached to the antenna.
- The value may be tailored to provide specific electrical responses.
- The RF ground connections should be kept as short as possible and connected to directly to a good RF ground for best performance.

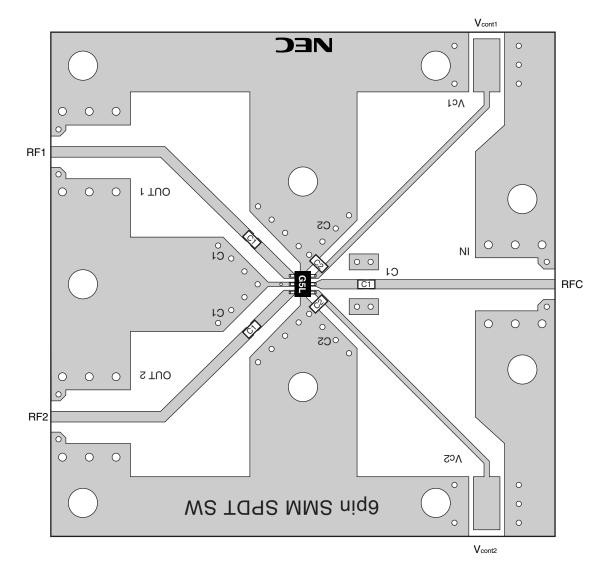
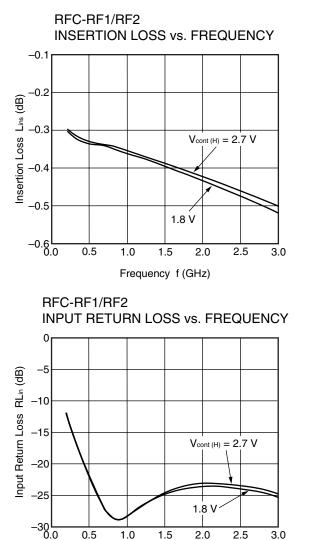


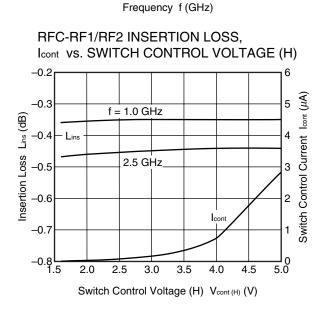
ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

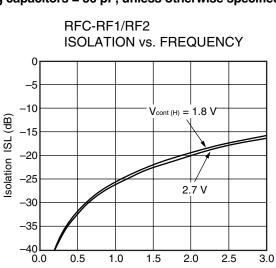
USING THE NEC EVALUATION BOARD

Symbol	Test Conditions	Values
C1	f = 0.01 to 0.05 GHz	10 000 pF
	f = 0.05 to 0.5 GHz	1 000 pF
	f = 0.5 to 3.0 GHz	56 pF
C2		1 000 pF

TYPICAL CHARACTERISTICS (T_A = +25°C, DC blocking capacitors = 56 pF, unless otherwise specified)

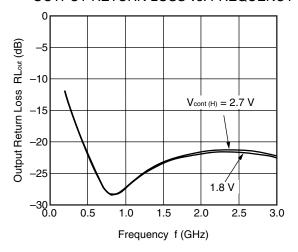




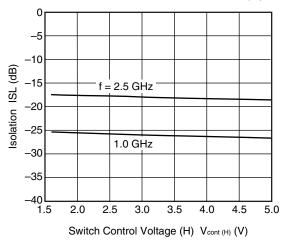


Frequency f (GHz)

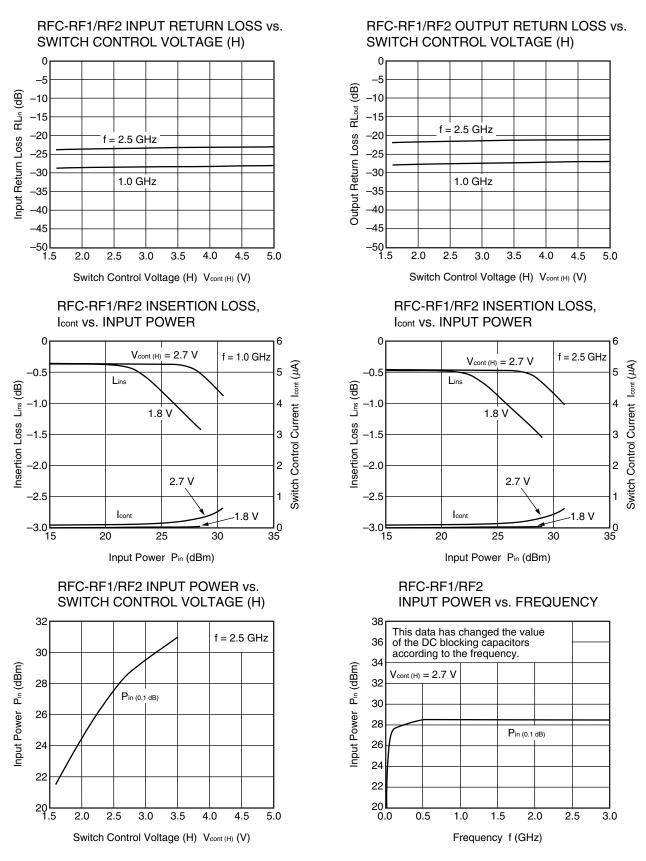
RFC-RF1/RF2 OUTPUT RETURN LOSS vs. FREQUENCY



RFC-RF1/RF2 ISOLATION vs. SWITCH CONTROL VOLTAGE (H)



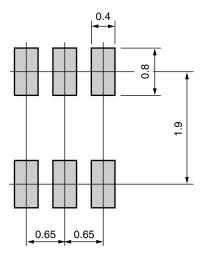




Remark The graphs indicate nominal characteristics.

MOUNTING PAD LAYOUT DIMENSIONS

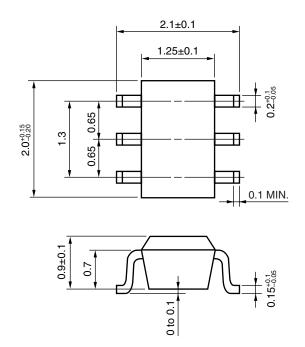
6-PIN SUPER MINIMOLD (UNIT: mm)



Remark The mounting pad layout in this document is for reference only.

PACKAGE DIMENSIONS

6-PIN SUPER MINIMOLD (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol	
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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April 1st, 2010 Renesas Electronics Corporation

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